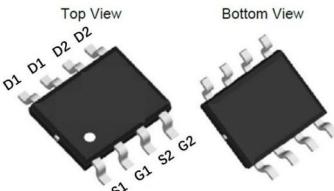
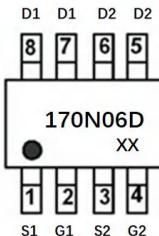




Description

JMT Dual N-channel Enhancement Mode Power MOSFET	
Features <ul style="list-style-type: none">• 60V, 9.2A• $R_{DS(ON)} < 20.4\text{m}\Omega$ @ $V_{GS} = 10\text{V}$• $R_{DS(ON)} < 24.4\text{m}\Omega$ @ $V_{GS} = 4.5\text{V}$• Advanced Trench Technology• Excellent $R_{DS(ON)}$ and Low Gate Charge• Lead Free	Application <ul style="list-style-type: none">• Load Switch• PWM Application• Power Management <p>100% UIS TESTED!</p> 
 SOP-8(Dual)	 Marking and pin Assignment

Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel (pcs)	Per Carton (pcs)
170N06D	JMTP170N06D	TAPING	SOP-8	13"	4000	48000

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		60	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ\text{C}$	9.2	A
		$T_A = 100^\circ\text{C}$	6	A
I_{DM}	Pulsed Drain Current ^{note1}		36.8	A
EAS	Single Pulsed Avalanche Energy ^{note2}		64	mJ
P_D	Power Dissipation	$T_A = 25^\circ\text{C}$	1.19	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		105	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	60	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60\text{V}$, $V_{GS}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1.0	1.6	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$, $I_D=9\text{A}$	-	16.3	20.4	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=5\text{A}$	-	18.8	24.4	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	2030	-	pF
C_{oss}	Output Capacitance		-	130	-	pF
C_{rss}	Reverse Transfer Capacitance		-	115	-	pF
Q_g	Total Gate Charge	$V_{DD}=30\text{V}$, $I_D=5\text{A}$, $V_{GS}=10\text{V}$	-	46	-	nC
Q_{gs}	Gate-Source Charge		-	7	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	10	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=30\text{V}$, $I_D=5\text{A}$, $R_{\text{GEN}}=1.8\Omega$, $V_{GS}=10\text{V}$	-	9	-	ns
t_r	Turn-on Rise Time		-	15	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	36	-	ns
t_f	Turn-off Fall Time		-	6	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	9.2	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	36.8	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=9.2\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$I_F=9\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$	-	16	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	13	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : Starting $T_J=25^\circ\text{C}$, $V_{DD}=30\text{V}$, $V_{GS}=10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$, $I_{AS}=16\text{A}$ 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

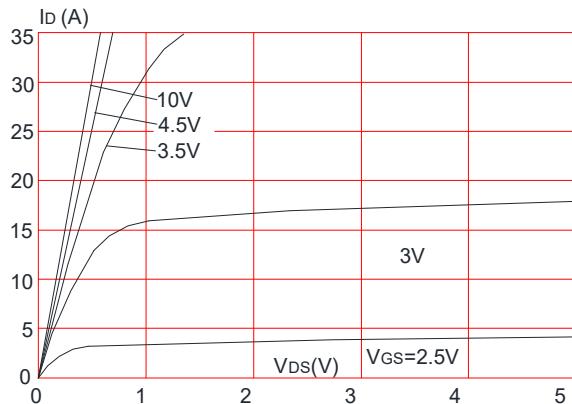


Figure 3: On-resistance vs. Drain Current

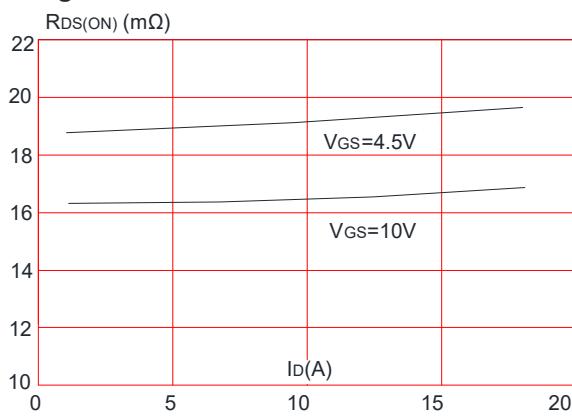


Figure 5: Gate Charge Characteristics

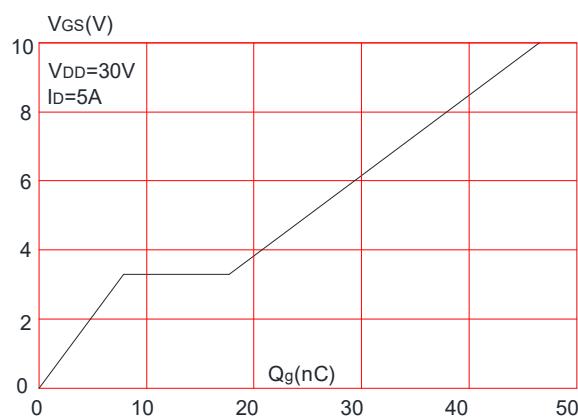


Figure 2: Typical Transfer Characteristics

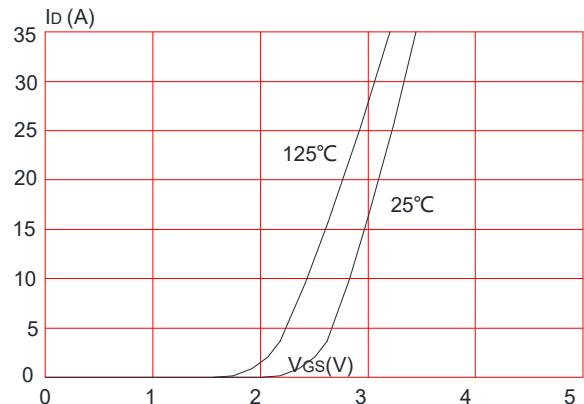


Figure 4: Body Diode Characteristics

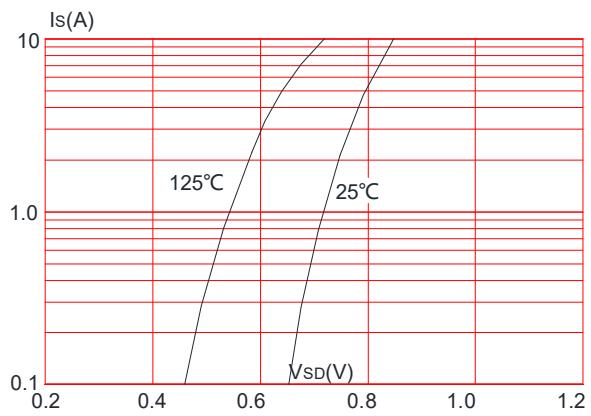


Figure 6: Capacitance Characteristics

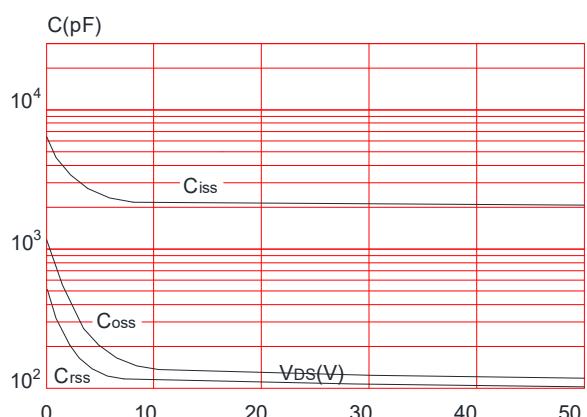


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

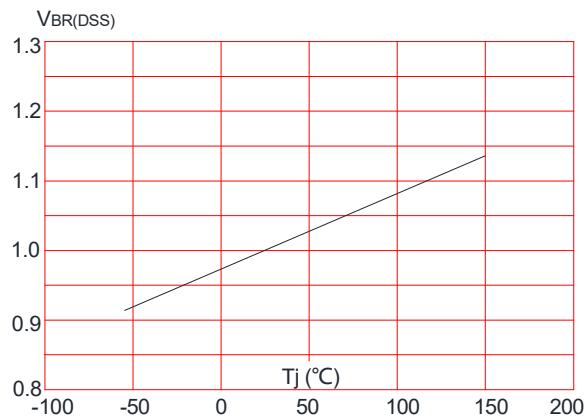


Figure 9: Maximum Safe Operating Area

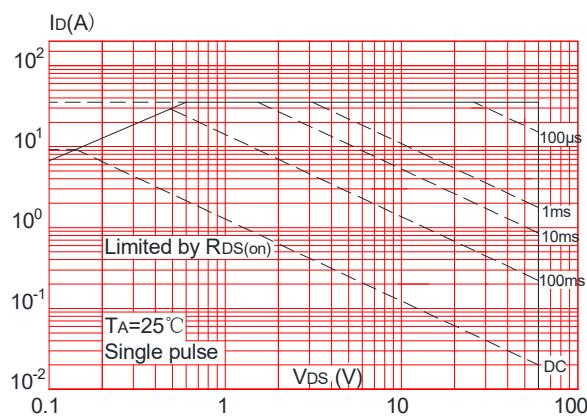


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

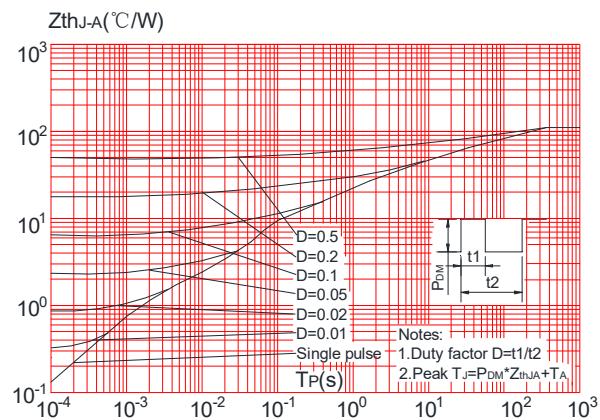


Figure 8: Normalized on Resistance vs. Junction Temperature

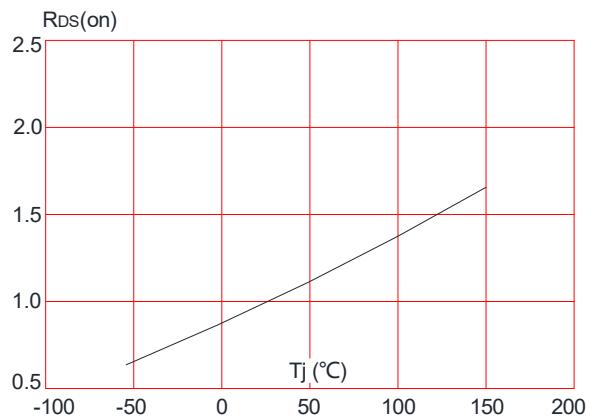
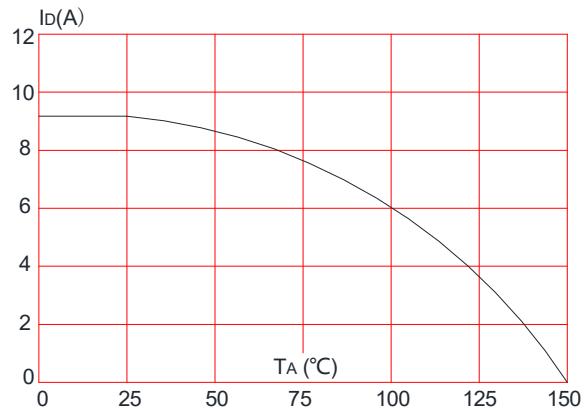


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature



Test Circuit

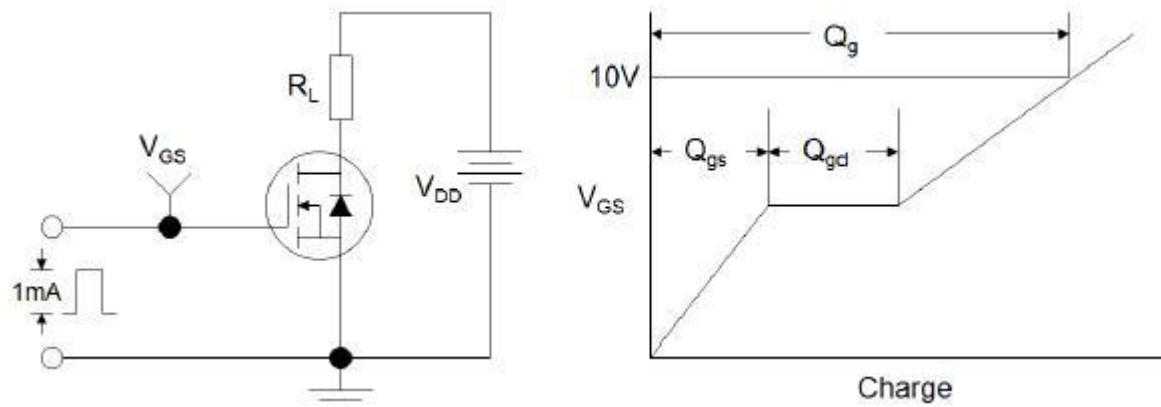


Figure 1: Gate Charge Test Circuit & Waveform

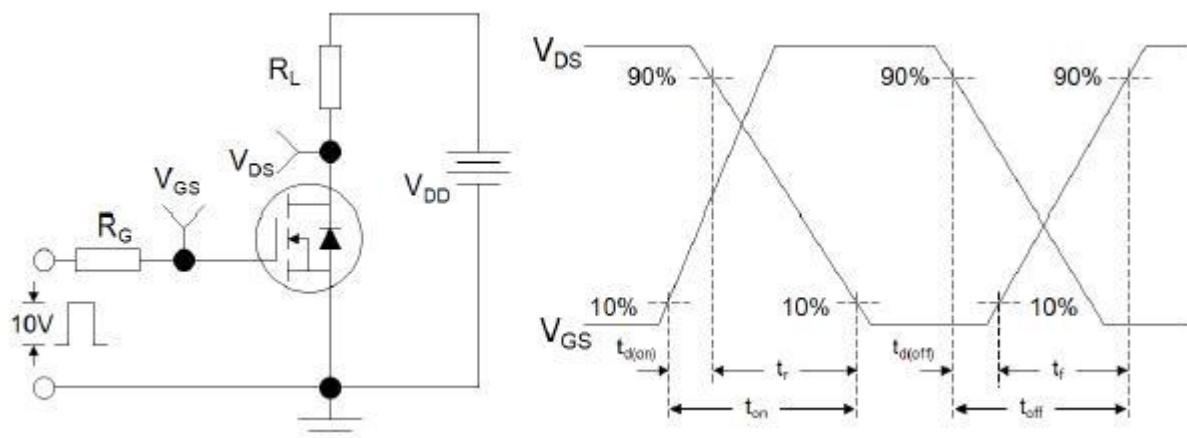


Figure 2: Resistive Switching Test Circuit & Waveforms

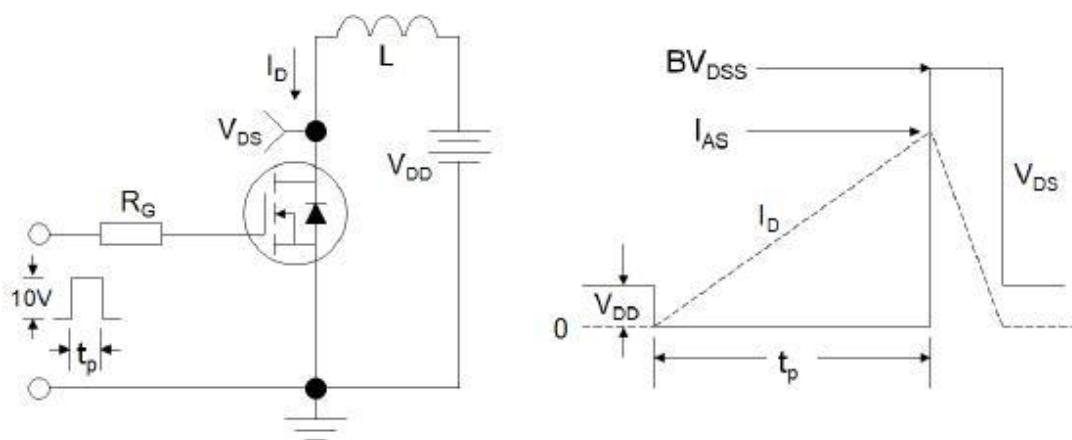
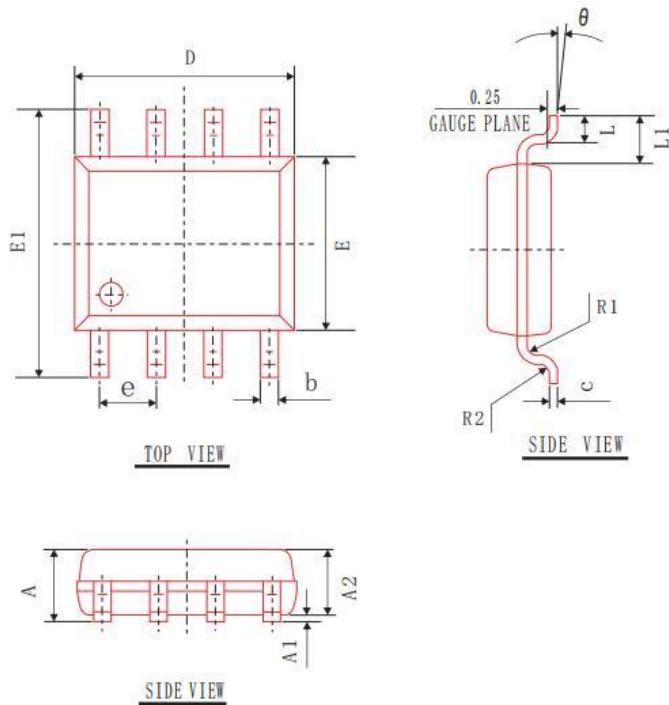


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms



Package Mechanical Data- SOP-8

COMMON DIMENSIONS
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	1.40	1.60	1.80
A1	0.05	0.15	0.25
A2	1.35	1.45	1.55
b	0.30	0.40	0.50
c	0.153	0.203	0.253
D	4.80	4.90	5.00
E	3.80	3.90	4.00
E1	5.80	6.00	6.20
L	0.45	0.70	1.00
θ	2°	4°	6°
L1	1.04 REF		
e	1.27 BSC		
R1	0.07 TYP		
R2	0.07 TYP		

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